PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3241918

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
WILLIAM MAINES	01/30/2015
DAVID MAINES	01/30/2015

RECEIVING PARTY DATA

Name:	ENDICOTT INTERCONNECT TECHNOLOGIES, INC.
Street Address:	1093 CLARK STREET
City:	ENDICOTT
State/Country:	NEW YORK
Postal Code:	13760

PROPERTY NUMBERS Total: 195

Property Type	Number
Application Number:	10322527
Application Number:	10370529
Application Number:	10379575
Application Number:	10394107
Application Number:	10394135
Application Number:	10409066
Application Number:	10423877
Application Number:	10423972
Application Number:	10616932
Application Number:	10630722
Application Number:	10643909
Application Number:	10661616
Application Number:	10679302
Application Number:	10737974
Application Number:	10740398
Application Number:	10740500
Application Number:	10790747
Application Number:	10811817
Application Number:	10811915

Property Type	Number
Application Number:	10812889
Application Number:	10812890
Application Number:	10860067
Application Number:	10860071
Application Number:	10882167
Application Number:	10882170
Application Number:	10900385
Application Number:	10900386
Application Number:	10915483
Application Number:	10920235
Application Number:	10933260
Application Number:	10953923
Application Number:	10955741
Application Number:	10968929
Application Number:	10991451
Application Number:	10991532
Application Number:	11031074
Application Number:	11031085
Application Number:	11086323
Application Number:	11086324
Application Number:	11110901
Application Number:	11110919
Application Number:	11110920
Application Number:	11127160
Application Number:	11128272
Application Number:	11152048
Application Number:	11172786
Application Number:	11172794
Application Number:	11177413
Application Number:	11177442
Application Number:	11215206
Application Number:	11216133
Application Number:	11238960
Application Number:	11242841
Application Number:	11244180
Application Number:	11258092
Application Number:	11259043
Application Number:	11265287

Property Type	Number
Application Number:	11281456
Application Number:	11305073
Application Number:	11324273
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Application Number:	11352276
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Application Number:	11396711
Application Number:	11397713
Application Number:	11401401
Application Number:	11429990
Application Number:	11438424
Application Number:	11454896
Application Number:	11455183
Application Number:	11482945
Application Number:	11492029
Application Number:	11500328
Application Number:	11541776
Application Number:	11590888
Application Number:	11598647
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Application Number:	11634287
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Application Number:	11652633
Application Number:	11727314
Application Number:	11730212
Application Number:	11730404
Application Number:	11730761
Application Number:	11730942
Application Number:	11783306
Application Number:	11797232
Application Number:	11797236

Property Type	Number
Application Number:	11802434
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Application Number:	11976629
Application Number:	12003299
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Application Number:	12007820
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Application Number:	12764993

Property Type	Number
Application Number:	12764994
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Application Number:	12910020
Application Number:	12938759
Application Number:	12939659
Application Number:	12972700
Application Number:	13009922
Application Number:	13022654
Application Number:	13041655
Application Number:	13042578
Application Number:	13082444
Application Number:	13082502
Application Number:	13082599
Application Number:	13090676
Application Number:	13184699
Application Number:	13184882
Application Number:	13189980
Application Number:	13197804
Application Number:	13198756
Application Number:	13238392
Application Number:	13239544
Application Number:	13252256
Application Number:	13269770
Application Number:	13358716
Application Number:	13360935

Property Type	Number
Application Number:	13362135
Application Number:	13442957
Application Number:	13447644
Application Number:	13447701
Application Number:	13448505
Application Number:	13448574
Application Number:	13448778
Application Number:	13456535
Application Number:	13466164
Application Number:	13466181
Application Number:	13476052
Application Number:	13483600
Application Number:	13517776
Application Number:	13523956
Application Number:	13535432
Application Number:	13540645
Application Number:	13594939
Application Number:	13600332
Application Number:	13610976
Application Number:	13622478
Application Number:	13626961
Application Number:	13682805
Application Number:	13723912
Application Number:	13776777

CORRESPONDENCE DATA

Fax Number: (607)723-6605

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6072316830

Email: amanzer@hhk.com

Correspondent Name: MARK LEVY, HINMAN, HOWARD & KATTELL, LLP

Address Line 1: 80 EXCHANGE STREET

Address Line 2: P.O. BOX 5250

Address Line 4: BINGHAMTON, NEW YORK 13901

NAME OF SUBMITTER:	MARK LEVY
SIGNATURE:	/Mark Levy/
DATE SIGNED:	02/26/2015

Total Attachments: 15

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TERMINATION OF SECURITY INTEREST IN TRADEMARKS AND PATENTS

WHEREAS, Endicott Interconnect Technologies, Inc., a New York corporation with its principal place of business at 1093 Clark Street, Endicott, NY 13760 (the "Grantor"), is the owner of record of the trademarks and applications listed on the attached Exhibit A, now issued or pending in the United States Patent and Trademark Office (the "Trademarks"); and is the owner of record of the patents and patent applications listed on the attached Exhibit B, now issued or pending in the United States Patent and Trademark Office (the "Patents"); and

WHEREAS, the Grantor entered into that certain Security Agreements dated as of June 12, 2013 (the "Security Agreement"), between the Grantor and William Maines and David Maines, ("Secured Party"), true and correct copies of which were recorded by the United States Patent and Trademark Office on June 12, 2013, at Reel 5045, Frame 0951 and Reel 30599, Frame 0918;

WHEREAS, the Secured Party desires to release its security interest in the Trademarks and Patents and terminate the Security Agreement;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, Secured Party hereby:

1. releases and reassigns to the Grantor any and all liens, security interests, right, title and interest of Secured Party pursuant to the Security Agreement in the trademarks and applications more fully described on Exhibit A, without recourse or representation or warranty, express or implied; and

2. releases and reassigns to the Grantor any and all liens, security interests, right, title and interest of Secured Party pursuant to the Security Agreement in the patents and applications more fully described on Exhibit B, without recourse or representation or warranty, express or implied; and

3. authorizes and requests the Commissioner of Patents and Trademarks of the United States of America to note and record the existence of the release hereby given.

IN WITNESS WHEREOF, Secured Party has caused this Termination of Security Interest in Trademarks and Patents to be signed by its duly authorized representative as of this 30th day of January, 2015.

Secured Parties:

William Maines

STATE OF NEW YORK)
) ss:
COUNTY OF BROOME)

On this 30th day of January, 2015, before me personally came William Maines, to me personally known, and known to me to be the person described in and who executed the foregoing affidavit, and she acknowledged to me that she executed the same as his free act and deed.

Notary

Karen H. Chier
Notary Public, State of New York
Qualified in Broome County
Commission Expires June 12, 2018
#01CH6043070

David Maines

STATE OF NEW YORK)
) ss:
COUNTY OF BROOME)

On this 30th day of January, 2015, before me personally came David Maines, to me personally known, and known to me to be the person described in and who executed the foregoing affidavit, and she acknowledged to me that she executed the same as his free act and deed.

Notary

Karen H. Chier
Notary Public, State of New York
Qualified in Broome County
Commission Expires June 12, 2018
#01CH6043070

Trademark/Service Mark	Country	Filing Date	Application No.	Registration No.	Registration Date	Status
COREEZ	US	3/24/2006	76/657,204	3,619,679	5/12/2009	Registered; Declaration of Use Due 5/12/2015
CoreEZ	US	3/24/2006	76/657,205	3,564,994	1/20/2009	Registered; Declaration of Use Due 1/20/2015
DRICLAD	US	7/31/1997	75/333,605	2,594,509	7/16/2002	Registered; Renewal Due 7/16/2022
DRICLAD	Brazil	1/22/1998	820508039	820508039	1/27/2009	Registered; Renewal Due 1/27/2019
DRICLAD	China		9800105902	1435500	8/21/2000	Registered; Renewal Due 8/20/2020
DRICLAD	France	5/9/2000		721563	7/23/2001	Registered; Renewal Due 12/30/2017
DRICLAD	Japan	11/14/1997	H09-177086	4245007	2/26/1999	Registered; Renewal Due 8/26/2018
DRICLAD	Korea	9/10/1998	1998-0023497	456079	9/29/1999	Registered; Renewal Due 10/6/2019
DRICLAD	Mexico	1/30/1998		572578		Registered; Renewal Due 1/30/2018
DRICLAD	Taiwan			108344		Registered; Renewal Due 7/15/2020
DRICLAD	Taiwan			896915		Registered; Renewal Due 3/31/2019
Endicott Interconnect	US	12/16/2002	76/476,536	2,831,497	4/13/2004	Registered
ENDICOTT INTERCONNECT 3D Design Only	US	6/20/2012	85/656,675			Pending
ENDICOTT INTERCONNECT 3D Design Only	UK	8/13/2012	2631552			Pending
ENDICOTT INTERCONNECT and 3D Design	US	6/20/2012	85/656,712			Pending
ENDICOTT INTERCONNECT and 3D Design	UK	8/13/2012	2631295			Pending
Endicott Interconnect Technologies	US	12/16/2002	76/476,537	2,829,453	4/6/2004	Registered; Renewal Due 4/6/2014
HYPERBGA	US	11/9/1999	75/844,816	2,632,339	10/8/2002	Registered; Renewal Due 10/8/2022
HYPERBGA	Australia	2/24/2000	824959	824959	2/16/2001	Registered; Renewal Due 2/24/2020
HYPERBGA	Canada	8/10/2004	1226508	TMA642449	6/20/2005	Registered; Renewal Due 12/20/2019
HYPERBGA	Canada		1044049			Registered; Renewal Due 6/19/2020
HYPERBGA	Singapore		TOO/10304A	T00/10304A	6/14/2000	Registered; Renewal Due 6/14/2020
HYPERBGA	Switzerland			477543		Registered; Renewal Due 5/5/2020
HYPERBGA	Taiwan			950034		Registered; Renewal Due 7/5/2021
HYPERBGA	Europe	5/9/2000	1645605	1645605	7/23/2001	Registered; Renewal Due 5/9/2020

Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-03-002	United States	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	2/24/2003	10/370,529	2004-0163964	6/14/2005	6,905,589	Issued
CA-2-03-002	Canada	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME		2452178			2,452,178	Issued
2-02-001	US	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/19/2002	10/322,527	2004-0118596	10/26/2004	6,809,269	Issued
CA-2-02-001	Canada	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/5/2003	2452178		5/13/2008	2,452,178	Issued
CN-2-02-001	China	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/19/2003	200310123253.X			ZL20031012 3253	Issued
2-02-001-CIP	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE	3/6/2003	10/379,575	2004-0118598	3/29/2005	6,872,894	Issued
2-02-001-CIPD	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE	9/3/2004	10/933,260	2005-0023035	5/31/2005	6,900,392	Issued
2-02-001D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE ASSEMBLY	3/30/2004	10/811,915	2004-0177998	5/23/2006	7,047,630	Issued
2-02-001D2	US	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	8/11/2004	10/915,483	2005-0011670	7/4/2006	7,071,423	Issued
2-02-001D3	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE ASSEMBLY	2/9/2006	11/349,998	2006-0123626	3/18/2008	7,343,674	Issued
CA-2-03-001	Canada	HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION	12/29/2003	2454289		5/13/2008	2,454,289	Issued
TW-2-03-001	Taiwan	HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION		93101219				Issued
2-03-001-CIP1	US	MULTI-CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	3/24/2003	10/394,107	2004-0150114	4/25/2006	7,035,113	Issued
2-03-001-CIP2	US	INFORMATION HANDLING SYSTEM	3/24/2003	10/394,135	2004-0150101	4/4/2006	7,023,707	Issued
2-03-001D	US	METHOD OF MAKING HIGH SPEED CIRCUIT BOARD	3/30/2004	10/811,817	2004-0231888	12/26/2006	7,152,319	Issued
2-03-007	US	METHOD OF TESTING SPACINGS IN PATTERN OF OPENINGS IN PCB CONDUCTIVE LAYER	7/11/2003	10/616,932	2005-0005438	3/21/2006	7,013,563	Issued
2-03-003	US	MATERIAL SEPARATION TO FORM SEGMENTED PRODUCT	4/9/2003	10/409,066	2004-0201136	10/25/2005	6,958,106	Issued
2-03-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/7/2003	10/679,302	2005-0074924	8/1/2006	7,084,014	Issued
2-03-011D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/26/2005	11/258,092	2006-0040426	1/16/2007	7,163,847	Issued
2-03-011D2	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/27/2005	11/259,043	2006-0046462	8/15/2006	7,091,066	Issued
2-03-009	US	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	8/20/2003	10/643,909	2005-0039840	6/20/2006	7,063,762	Issued
2-03-009D	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE POLYMER AND SEED MATERIALS ADHESION LAYER	10/5/2005	11/242,841	2006-0029781	2/19/2008	7,332,212	Issued
2-03-008	US	ELECTRONIC COMPONENT TEST APPARATUS	7/31/2003	10/630,722	2005-0022376	9/19/2006	7,109,732	Issued
TW-2-03-006	Taiwan	ELECTRONIC CARD		93114136				Pending
2-03-004-CIP	US	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	4/28/2003	10/423,877	2004-0183212	11/9/2004	6,815,837	Issued
EP-2-03-004-CIP	Europe	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD		4250754.1				Pending
TW-2-03-004-CIP	Taiwan	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	2/11/2004	93103172		8/1/2007	I284967	Issued
2-03-005-CIP	US	PINNED ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	4/28/2003	10/423,972	2004-082604	8/8/2006	7,087,846	Issued
2-05-002	US	ELECTRONIC CARD ASSEMBLY	3/23/2005	11/086,324	2006-0213973	10/28/2008	7,441,709	Issued
2-04-003	US	CIRCUITIZED SUBSTRATE	3/31/2004	10/812,890	2005-0224985	7/18/2006	7,078,816	Issued
EP-2-04-003	Europe	CIRCUITIZED SUBSTRATE		5251748.9				Pending
2-04-003D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	2/9/2006	11/349,990	2006-0131755	8/26/2008	7,416,996	Issued
2-04-003D2	US	INFORMATION HANDLING SYSTEM UTILIZING A CIRCUITIZED SUBSTRATE HAVING A DIELECTRIC LAYER WITHOUT CONTINUOUS FIBERS	2/10/2006	11/350,777	2006-0125103	3/24/2009	7,508,076	Issued
2-04-005	US	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES	3/31/2004	10/812,889	2008-0008727	9/18/2007	7,270,845	Issued
EP-2-04-005	Europe	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES		5251747.1				Pending
TW-2-04-005	Taiwan	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES	3/18/2005	94108442				Pending

Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-04-005D	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC LAYER HAVING DIELECTRIC COMPOSITION NOT INCLUDING CONTINUOUS OR SEMI-CONTINUOUS FIBERS	9/6/2007	11/896,786	2008-0003407			Allowed
2-03-001-CIP3	US	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	9/15/2003	10/661,616	2004-0150095	1/31/2006	6,992,896	Issued
TW-2-03-001-CIP3	Taiwan	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME		93101178				Issued
2-03-001-CIP3C	US	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	9/30/2005	11/238,960	2006-0023439	1/9/2007	7,161,810	Issued
2-03-001-CIP3CD	US	METHOD OF MAKING A MULTI-CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER	6/19/2006	11/455,183	2006-0240594	2/23/2010	7,665,207	Issued
2-04-011	US	CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILITIZING SAME	7/28/2004	10/900,385	2006-0022303	8/7/2007	7,253,502	Issued
TW-2-04-011		CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		94124018				Pending
2-04-011D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE	6/12/2007	11/808,596	2007-0249089	2/5/2008	7,326,643	Issued
2-04-014	US	ELECTRICAL ASSEMBLY WITH INTERNAL MEMORY CIRCUITIZED SUBSTRATE HAVING ELECTRONIC COMPONENTS POSITIONED THEREON, METHOD OF MAKING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/28/2004	10/900,386	2006-0022310	5/16/2006	7,045,897	Issued
2-07-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY	10/9/2007	11/907,006	2009-0092353	6/2/2009	7,541,058	Issued
CN-2-07-011	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY		200810168239.4				Pending
2-07-014	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY USING PHOTOLITHOGRAPHY	10/19/2007	11/907,004	2009-0093073	5/11/2010	7,713,767	Issued
CN-2-07-014	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY USING PHOTOLITHOGRAPHY	10/6/2008	200810168238.X				Pending
2-07-012	US	CIRCUITIZED SUBSTRATE WITH INTERNAL COOLING STRUCTURE AND ELECTRICAL ASSEMBLY UTILIZING SAME	10/25/2007	11/976,468	2009-0109624	6/15/2010	7,738,249	Issued
CN-2-07-012	China	CIRCUITIZED SUBSTRATE WITH INTERNAL COOLING STRUCTURE AND ELECTRICAL ASSEMBLY UTILIZING SAME	10/22/2008	200810171145.2				Pending
2-03-012	US	ITEM IDENTIFICATION CONTROL METHOD	12/22/2003	10/740,500	2005-0137890	9/21/2010	7,801,833	Issued
2-04-004	US	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	8/18/2004	10/920,235	2005-0224251	12/5/2006	7,145,221	Issued
2-04-007	US	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	3/23/2005	11/086,323	2005-0218524	12/30/2008	7,470,990	Issued
CN-2-04-007	China	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		200610057200.6				Pending

Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
EP-2-04-007	Europe	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		6251492.2				Pending
IN-2-04-007	India	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		355/DEL/2006				Pending
TW-2-04-007	Taiwan	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		95108059				Pending
2-04-007D	US	METHOD OF MAKING SAME LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION	4/5/2007	11/730,942	2007-0182016	8/26/2008	7,416,972	Issued
2-07-016	US	METHOD OF MAKING CIRCUITIZED SUBSTRATES HAVING FILM RESISTORS AS PART THEREOF	1/16/2008	12/007,820	2009-0178271	8/14/2012	8,240,027	Issued
2-05-020	US	CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRU-HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	4/11/2006	11/401,401	2006-0214010	3/16/2010	7,679,005	Issued
2-05-022	US	METHOD OF MAKING PRINTED CIRCUIT BOARD WITH VARYING DEPTH CONDUCTIVE HOLES ADAPTED FOR RECEIVING PINNED ELECTRICAL COMPONENTS	1/19/2006	11/334,445	2006-0121722			Pending
2-03-013	US	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE	12/22/2003	10/740,398	2005-0133257	2/13/2007	7,176,383	Issued
EP-2-03-013	Europe	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		4257721.3				Pending
JP-2-03-013	Japan	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		2004-349471				Pending
TW-2-03-013	Taiwan	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		93138054				Pending
2-03-013D	US	METHOD OF MAKING A PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE	12/6/2006	11/634,287	2007-0089290	5/12/2009	7,530,167	Issued
2-03-014	US	METHOD OF MAKING MULTILAYERED PRINTED CIRCUIT BOARD WITH FILLED CONDUCTIVE HOLES	12/18/2003	10/737,974	2005-0136646	5/1/2007	7,211,289	Issued
JP-2-03-014	Japan	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM		2004-355230				Pending
TW-2-03-014	Taiwan	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM	12/3/2004	93137509		1/1/2012	I355871	Pending
2-03-014D	US	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM	4/5/2006	11/397,713	2006-0183316	3/25/2008	7,348,677	Issued
2-04-002	US	CIRCUITIZED SUBSTRATE WITH SIGNAL WIRE SHIELDING, ELECTRICAL ASSEMBLY UTILIZING SAME AND METHOD OF MAKING	3/3/2004	10/790,747	2005-0195585	4/24/2007	7,209,368	Issued
2-04-002D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SIGNAL WIRE SHIELDING	5/9/2006	11/429,990	2006-0200977	12/9/2008	7,478,472	Issued
2-04-009	US	CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/2/2004	10/882,170	2006-0000639	1/2/2007	7,157,647	Issued
2-04-009D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER	7/10/2006	11/482,945	2006-0248717	10/19/2010	7,814,649	Issued
2-04-013	US	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/2/2004	10/882,167	2006-0000636	1/2/2007	7,157,646	Issued

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IN-2-04-013	India	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		1330/DEL/2005				Pending
TW-2-04-013	Taiwan	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	6/20/2005	94120469		10/1/2012	I373992	Issued
2-04-013D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER AND INFORMATION HANDLING SYSTEM UTILIZING SAME	12/20/2006	11/641,810	2007-0144772	5/27/2008	7,377,033	Issued
2-04-013DD	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER	1/18/2008	12/010,004	2008-0117583	2/17/2009	7,491,896	Issued
2-04-016	US	METHOD OF MAKING CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	11/19/2004	10/991,532	2006-0110898	6/10/2008	7,383,629	Issued
CN-2-04-016	China	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		200510115609.4				Pending
IN-2-04-016	India	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		2488/DEL/20058				Pending
2-04-016D	US	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	4/17/2008	12/148,271	2008-0259581	11/23/2010	7,838,776	Issued
2-04-016D2	US	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	8/11/2010	12/854,252	2010-0328868	8/14/2012	8,242,376	Issued
2-04-018	US	CIRCUITIZED SUBSTRATE WITH IMPROVED IMPEDANCE CONTROL CIRCUITRY, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	9/29/2004	10/953,923	2006-0065433	11/13/2007	7,294,791	Issued
2-04-018D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH IMPROVED IMPEDANCE CONTROL CIRCUITRY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM	8/15/2007	11/889,668	2007-0284140	9/15/2009	7,589,283	Issued
2-04-006	US	METHOD AND SYSTEM FOR TRACKING GOODS	6/4/2004	10/860,067	2005-0289019	6/23/2009	7,552,091	Issued
2-04-010	US	RADIO FREQUENCY DEVICE FOR TRACKING GOODS	6/4/2004	10/860,071	2005-0270160	11/28/2006	7,142,121	Issued
2-04-015	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE HAVING A PLURALITY OF SOLDER CONNECTION SITES THEREON	10/21/2004	10/968,929	2006-0099727	8/8/2006	7,087,441	Issued
2-04-008	US	HIGH SPEED CIRCUITIZED SUBSTRATE WITH REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME	9/30/2004	10/955,741	2005-0039950	2/7/2006	6,995,322	Issued
IN-2-04-008	India	HIGH SPEED CIRCUITIZED SUBSTRATE W/REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME		1828/DEL/2005				Pending
TW-2-04-008	Taiwan	HIGH SPEED CIRCUITIZED SUBSTRATE W/REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME		94132230				Pending
2-05-025	US	SUBSTRATE TEST APPARATUS AND METHOD OF TESTING SUBSTRATES	11/18/2005	11/281,456		10/31/2006	7,129,732	Issued
2-05-001	US	INTERPOSER FOR USE WITH TEST APPARATUS	4/21/2005	11/110,901	2006-0238207	11/6/2007	7,292,055	Issued
2-05-001D	US	METHOD OF MAKING AN INTERPOSER	9/27/2007	11/902,976	2008-0020566	3/31/2009	7,511,518	Issued

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2-05-014	US	WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN, METHOD OF MAKING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	6/15/2005	11/152,048	2006-0284304	8/7/2007	7,253,518	Issued
2-05-014D	US	METHOD OF MAKING WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN	7/9/2007	11/822,573	2007-0254408	3/31/2009	7,510,912	Issued
2-05-010	US	MULTI-CHIP ELECTRONIC PACKAGE WITH REDUCED LINE SKEW AND CIRCUITIZED SUBSTRATE FOR USE THEREIN	5/12/2005	11/127,160	2006-0255460	2/19/2008	7,332,818	Issued
2-05-010D	US	METHOD OF MAKING MULTI-CHIP ELECTRONIC PACKAGE WITH REDUCED LINE SKEW	12/21/2007	12/003,299	2008-0102562	11/24/2009	7,622,384	Issued
2-04-017	US	CAPACITOR MATERIAL FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/10/2005	11/031,085	2006-0151863	6/2/2009	7,541,265	Issued
CN-2-04-017	China	CIRCUITIZED SUBSTRATES, CAPACITOR MATERIAL THEREFOR, THEIR PREPARATION METHOD, AND INFORMATION HANDLING SYSTEM COMPRISING SAME	12/28/2005	200510097424.5				Allowed
IN-2-04-017	India	CAPACITOR MATERIAL FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATES		3154/DEL/2005				Pending
2-05-006	US	PLATING METHOD FOR CIRCUITIZED SUBSTRATES	5/13/2005	11/128,272	2006-0255009	1/30/2007	7,169,313	Issued
2-05-016	US	METHOD OF TREATING CONDUCTIVE LAYER FOR USE IN A CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE HAVING SAID CONDUCTIVE LAYER AS PART THEREOF	1/9/2006	11/327,493	2006-0121738	12/11/2007	7,307,022	Issued
2-05-016D	US	CIRCUITIZED SUBSTRATE WITH INCREASED ROUGHNESS CONDUCTIVE LAYER AS PART THEREOF	10/26/2007	11/976,629	2008-0054476			Pending
2-05-012	US	CIRCUITIZED SUBSTRATE WITH SINTERED PASTE CONNECTIONS, MULTILAYERED SUBSTRATE ASSEMBLY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/11/2005	11/177,442	2007-0007032	3/11/2008	7,342,183	Issued
2-05-012D	US	METHOD OF MAKING MULTILAYERED CIRCUITIZED SUBSTRATE ASSEMBLY	9/28/2007	11/905,188	2008-0022520	11/2/2010	7,823,274	Issued
2-05-013	US	METHOD OF MAKING MULTILAYERED CIRCUITIZED SUBSTRATE ASSEMBLY HAVING SINTERED PASTE CONNECTIONS	7/11/2005	11/177,413	2007-0006452	2/26/2008	7,334,323	Issued
2-05-013D	us	CIRCUITIZED SUBSTRATE WITH SINTERED PASTE CONNECTIONS AND MULTILAYERED SUBSTRATE ASSEMBLY HAVING SAID SUBSTRATE AS PART THEREOF	1/8/2008	12/007,178	2008-0105457			Pending
2-04-019	US	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME	11/19/2004	10/991,451		11/15/2005	6,964,884	Issued
CN-2-04-019	China	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		200510115610.7				Pending
IN-2-04-019	India	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		2489/DEL/2005				Pending

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2-04-019D	US	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME	8/31/2005	11/215,206	2006-0180343			Pending
2-05-003	US	APPARATUS AND METHOD FOR MAKING CIRCUITIZED SUBSTRATES IN A CONTINUOUS MANNER	4/21/2005	11/110,919		11/13/2007	7,293,355	Issued
2-05-003D	US	APPARATUS FOR MAKING CIRCUITIZED SUBSTRATES IN A CONTINUOUS MANNER	8/3/2007	11/882,625	2007-0266555	2/12/2008	7,328,502	Issued
2-05-005	US	APPARATUS FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER	4/21/2005	11/110,920	2006-0240364	11/9/2010	7,827,682	Issued
2-05-005D	US	METHOD FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER	1/20/2010	12/657,394	2011-0173809	7/12/2011	7,977,034	Issued
2-05-017	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	1/4/2006	11/324,432	2007-0166944	6/3/2008	7,381,587	issued
CN-2-05-017	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE	12/21/2006	200610170522.1		7/11/2007	1,996,562	issued
TW-2-05-017	Taiwan	METHOD OF MAKING CIRCUITIZED SUBSTRATE	12/21/2006	95148292	95148292			Pending
2-04-020	US	CAPACITOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/10/2005	11/031,074		4/11/2006	7,025,607	Issued
2-04-020D	US	CAPACITOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/4/2006	11/324,273	2006-0154501			Pending
2-05-008	US	METHOD OF MAKING AN INTERNAL CAPACITIVE SUBSTRATE FOR USE IN A CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE	7/5/2005	11/172,794	2006-0154434	6/10/2008	7,384,856	Issued
2-05-009	US	RESISTOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	7/5/2005	11/172,786	2006-0151202	7/13/2006	7,235,745	Issued
2-05-009D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH A RESISTOR	5/2/2007	11/797,236	2008-0151515	1/18/2011	7,870,664	Issued
2-05-009D2	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH RESISTOR INCLUDING MATERIAL WITH METAL COMPONENT AND ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	11/3/2010	12/938,759	2011-0043987	8/21/2012	8,247,703	Issued
2-05-018	US	METHOD OF IMPROVING ELECTRICAL CONNECTIONS IN CIRCUITIZED SUBSTRATES	12/19/2005	11/305,073	2007-0139977	12/8/2009	7,629,559	Issued
2-05-015	US	METHOD AND APPARATUS FOR DEPOSITING CONDUCTIVE PASTE IN CIRCUITIZED SUBSTRATE OPENINGS	9/1/2005	11/216,133	2007-0048897	5/1/2007	7,211,470	Issued
2-06-001	US	ADJUSTABLE THICKNESS THERMAL INTERPOSER AND ELECTRONIC PACKAGE UTILIZING SAME	4/4/2006	11/396,711	2007-0230130	12/8/2009	7,629,684	Issued
2-05-028	US	METHOD OF FORMING FIBROUS LAMINATE CHIP CARRIER STRUCTURES	7/16/2010	12/837,584	2012-0012553			Pending
2-06-004	US	CAPACITIVE SUBSTRATE	5/23/2006	11/438,424	2007-0275525	3/1/2011	7,897,877	Issued
2-06-004D	US	CAPACITIVE SUBSTRATE AND METHOD OF MAKING SAME	3/2/2009	12/380,616	2009-0206051	9/28/2010	7,803,688	Issued
2-08-009	US	PHOTOSENSITIVE DIELECTRIC FILM	7/27/2009	12/460,975	2011-0017498			Pending
JP-2-05-023	Japan	METHOD OF MAKING A CIRCUITIZED SUBSTRATE HAVING A PLURALITY OF SOLDER CONNECTION SITES THEREON		2006-267024				Pending

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2-05-019	US	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME	11/3/2005	11/265,287	2006-0054870	4/26/2011	7,931,830	Issued
IN-2-05-019	India	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2164/DEL/2006				Pending
JP-2-05-019	Japan	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2006-288641				Pending
2-05-021	US	CIRCUITIZED SUBSTRATE WITH SOLDER-COATED MICROPARTICLE PASTE CONNECTIONS, MULTILAYERED SUBSTRATE ASSEMBLY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZIGN SAME AND METHOD OF MAKING SAID SUBSTRATE	10/6/2005	11/244,180	2007-0007033	10/28/2008	7,442,879	Issued
2-06-010	US	INTERPOSER AND TEST ASSEMBLY FOR TESTING ELECTRONIC DEVICES	12/4/2006	11/607,973	2007-0075726	3/10/2009	7,501,839	Issued
2-05-024	US	FLUOROPOLYMER DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME	3/28/2006	11/390,386	2006-0180936	9/30/2008	7,429,789	Issued
JP-2-05-024	Japan	FLUOROPOLYMER DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2007-081228				Pending
2-06-002	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS	11/14/2006	11/598,647	2008-0110016	6/16/2009	7,547,577	Issued
CN-2-06-002	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS	11/5/2007	200710165173.9				Issued
IN-2-06-002	India	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS		2156/DEL/2007				Pending
TW-2-06-002	Taiwan	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS		96138518				Pending
2-05-026	US	METHOD OF MAKING A CAPACITIVE SUBSTRATE FOR USE AS PART OF A LARGER CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING AN INFORMATION HANDLING SYSTEM INCLUDING SAID CIRCUITIZED SUBSTRATE	2/13/2006	11/352,279	2007-0010065	11/11/2008	7,449,381	Issued
2-05-027	US	METHOD OF MAKING A CAPACITIVE SUBSTRATE USING PHOTOIMAGEABLE DIELECTRIC FOR USE AS PART OF A LARGER CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING AN INFORMATION HANDLING SYSTEM INCLUDING SAID CIRCUITIZED SUBSTRATE	2/13/2006	11/352,276	2007-0010064	9/30/2008	7,429,510	Issued
2-07-001	US	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN	1/12/2007	11/652,633	2008-0168651	10/6/2009	7,596,863	Issued
HK-2-07-001	Hong Kong	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN		9103246.7				Pending
IN-2-07-001	India	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN		2709/DEL/2007				Pending
2-06-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY	1/8/2007	11/650,520	2008-0164300			Pending
2-06-015	US	CRENELLATED ISOLATION BORDER STRUCTURE AND METHOD	4/26/2012	13/456,535				Pending

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2-06-009	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE WITH ENHANCED CIRCUITRY AND ELECTRICAL ASSEMBLY UTILIZING SAID SUBSTRATE	11/1/2006	11/590,888	2008-0098595	9/29/2009	7,595,454	Issued
2-06-006	US	HIGH SPEED INTERPOSER	6/19/2006	11/454,896	2007-0289773	12/8/2009	7,629,541	Issued
2-06-006D1	US	HIGH SPEED INTERPOSER	1/24/2008	12/010,335	2008-0142258	1/25/2011	7,875,811	Issued
2-06-005	US	PHOTORESIST COMPOSITION WITH ANTIBACTERIAL AGENT	7/25/2006	11/492,029	2008-0026316	12/22/2009	7,635,552	Issued
2-06-007	US	SOLDER MASK APPLICATION PROCESS	8/8/2006	11/500,328	2008-0038670	10/16/2012	8,288,266	Issued
2-06-007D	US	CIRCUITIZED SUBSTRATE ASSEMBLY	9/12/2012	13/610,976				Pending
2-06-014	US	PRINTED CONDUCTIVE LINES WITH LOW RESISTIVITY	7/18/2011	13/184,699				Pending
2-06-008	US	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	10/3/2006	11/541,776	2008-0078570	3/30/2010	7,687,722	Issued
CN-2-06-008	China	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		200710161542.7				Pending
IN-2-06-008	India	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		2044/DEL/2007				Pending
2-06-008D	US	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	3/2/2009	12/380,618	2009-0175000			Pending
2-07-003	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SELECTED CONDUCTORS HAVING SOLDER THEREON	3/30/2007	11/730,212	2008-0241359	3/22/2011	7,910,156	Issued
2-06-016	US	CAPACITOR MATERIAL, CIRCUITIZED SUBSTRATE HAVING INTERNAL CAPACITOR COMPRISED OF SAID MATERIAL THEREIN AND ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE	7/3/2012	13/540,645				Pending
2-07-002	US	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS	3/26/2007	11/727,314	2008-0237840	12/14/2010	7,851,906	Issued
IN-2-07-002	India	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		422/DEL/2008				Pending
JP-2-07-002	Japan	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		2008-057976				Pending
TW-2-07-002	Taiwan	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		97106659				Pending
2-07-005	US	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE	5/2/2007	11/797,232	2007-0199195	12/8/2009	7,627,947	Issued
CN-2-07-005	China	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE	4/30/2008	200810094487.9	101299911			Issued
IN-2-07-005	India	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		887/DEL/2008				Pending
EP-2-07-005	Europe	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		8251545.3				Pending
JP-2-07-005	Japan	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		2008-114868				Pending
2-06-013	US	NON-FLAKING CAPACITOR MATERIAL, CAPACITIVE SUBSTRATE HAVING AN INTERNAL CAPACITOR THEREIN INCLUDING SAID NON-FLAKING CAPACITOR MATERIAL, AND METHOD OF MAKING A CAPACITOR MEMBER FOR USE IN A CAPACITIVE SUBSTRATE	4/4/2007	11/730,761	2007-0177331			Pending
2-07-006	US	ADHESIVE BLEED PREVENTION METHOD AND PRODUCT PRODUCED FROM SAME	7/31/2007	11/882,149	2009-0035455			Pending

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2-06-012	US	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME	4/9/2007	11/783,306	2008-0244902	9/21/2010	7,800,916	Pending
EP-2-06-012	Europe	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		8251098.3				Pending
JP-2-06-012	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		2008-098245				Pending
TW-2-06-012	Taiwan	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		97111078				Pending
2-06-026	US	SINTERED METAL MIXTURE FOR Z-AXIS ELECTRICAL INTERCONNECTION	9/26/2012	13/626,961				Pending
2-07-008	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE PASTE, ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE	5/23/2007	11/802,434	2007-0221404	11/22/2011	8,063,315	Issued
2-07-008D	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE PASTE, ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE	10/4/2011	13/252,256	2012-0017437			Pending
IN-2-07-008	India	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		912/DEL/2008				Pending
JP-2-07-008	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		2008-127348				Pending
2-06-029	US	ELECTRICALLY CONDUCTIVE ADHESIVE (ECA) FOR MULTILAYER DEVICE INTERCONNECTS	8/5/2011	13/198,756	2013-0033827			Pending
2-07-009	US	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION	6/7/2007	11/808,140	2008-0301933	5/11/2010	7,712,210	Issued
2-07-013	US	POWER CORE FOR USE IN CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	5/18/2010	12/782,187	2011-0284273	6/12/2012	8,198,551	Issued
2-08-003	US	HIGH BANDWIDTH SEMICONDUCTOR BALL GRID ARRAY PACKAGE	11/4/2010	12/939,659	2012-0112345			Pending
2-07-004	US	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME	4/2/2007	11/730,404	2008-0238323	11/30/2010	7,841,741	Issued
HK-2-07-004	Hong Kong	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME		9103287.7				Pending
IN-2-07-004	India	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME		642/DEL/2008				Pending
2-07-010C	US	SUBSTRATE HAVING INTERNAL CAPACITOR AND METHOD OF MAKING SAME	6/14/2012	13/517,776				Pending
2-07-040	US	DEFECTIVE CONDUCTIVE SURFACE PAD REPAIR FOR MICROELECTRONIC CIRCUIT CARDS	3/7/2011	13/041,655	2012-0228013			Pending
2-07-007	US	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE	6/4/2007	11/806,685	2008-0087459	3/30/2010	7,687,724	Issued

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JP-2-07-007	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		2008-145499				Pending
TW-2-07-007	Taiwan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		97118394				Pending
EI-2-07-007D	US	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE	10/20/2009	12/589,239	2011-0039212			Pending
2-07-015	US	METHOD OF MAKING CIRCUITIZED ASSEMBLY INCLUDING A PLURALITY OF CIRCUITIZED SUBSTRATES	1/15/2008	12/007,704	2009-0178273			Pending
2-08-001	US	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	3/28/2008	12/078,206	2009-0241332			Pending
2-08-010	US	METHOD OF FORMING MULTILAYER CAPACITORS IN A PRINTED CIRCUIT SUBSTRATE	10/22/2010	12/909,983	2012-0223047			Pending
2-07-023	US	METHOD FOR IMPREGNATING ORGANIC FIBER PAPERS, INCLUDING P-ARAMID PAPERS	7/7/2010	12/831,411				Pending
2-07-017	US	CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	4/10/2008	12/081,051	2008-0191354	12/27/2011	8,084,863	Issued (CIP of EI-2-04-007)
2-07-017D	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE WITH CONTINUOUS THERMOPLASTIC SUPPORT FILM DIELECTRIC LAYERS	3/2/2009	12/380,637	2009-0258161			Pending
2-08-002	US	MULTILAYERED CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	4/10/2008	12/081,042	2008-0191353	1/12/2010	7,646,098	Issued
2-08-002D	US	MULTILAYERED CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	3/2/2009	12/380,617	2009-0173426	7/3/2012	8,211,790	Issued
2-07-028	US	CONDUCTIVE METAL NUB FOR ENHANCED ELECTRICAL INTERCONNECTION, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	1/20/2011	13/009,922	2012-0243155			Pending
2-08-007	US	SPRING ACTUATED CLAMPING MECHANISM	6/25/2008	12/215,079	2009-0320280	10/4/2011	8,028,390	Issued
2-08-007D	US	METHOD OF APPLYING FORCE TO ELECTRICAL CONTACTS ON A PRINTED CIRCUIT BOARD	4/20/2011	13/090,676	2011-0197430	6/12/2012	8,196,281	Issued
2-08-023	US	CONDUCTIVE PASTE FOR DEVICE LEVEL INTERCONNECTS	9/17/2010	12/884,657	2012-0069531			Pending
2-08-006	US	A METHOD OF JOINING A SEMICONDUCTOR DEVICE/CHIP TO A PRINTED WIRING BOARD	7/16/2010	12/837,640	2012-0015532	8/14/2012	8,240,031	Issued
2-08-008	US	MULTI-LAYER EMBEDDED CAPACITANCE AND RESISTANCE SUBSTRATE CORE	9/9/2008	12/283,146	2010-0060381	9/7/2010	7,791,897	Issued
2-08-008D	US	MULTI-LAYER EMBEDDED CAPACITANCE AND RESISTANCE SUBSTRATE CORE	3/10/2010	12/720,849	2010-0167210	3/27/2012	8,144,480	Issued
2-08-024	US	METHOD FOR VIA PLATING IN ELECTRONIC PACKAGES CONTAINING FLUOROPOLYMER DIELECTRIC LAYERS	4/22/2010	12/765,110	2011-0260299			Pending
2-08-012	US	LIQUID CRYSTAL POLYMER LAYER FOR ENCAPSULATION AND IMPROVED HERMITICITY OF CIRCUITIZED SUBSTRATES	9/17/2010	12/884,392	2012-0069288	3/27/2012	8,143,530	Issued
2-08-016	US	SILICON INTERPOSER CONTAINING ACTIVE COMPONENTS AND AN INTEGRATED CONNECTOR	1/31/2012	13/362,135				Pending
2-08-025	US	NEW HIGH DENSITY PACKAGING-COMPUTING SYSTEM	4/8/2011	13/082,599	2012-0260063			Pending
2-08-021-1	US	CORELESS LAYER BUILDUP STRUCTURE	4/22/2010	12/764,993	2012-0160547			Pending
2-08-021-2	US	CORELESS LAYER BUILDUP STRUCTURE WITH LGA	4/22/2010	12/764,994	2012-0160544			Pending
2-08-021-3	US	CORELESS LAYER BUILDUP STRUCTURE WITH LGA AND JOINING LAYER	4/22/2010	12/764,997	2012-0031649			Pending
2-09-002	US	CONDUCTIVE PASTE COMPOSITION AND METHOD OF MAKING CIRCUITIZED SUBSTRATE	4/8/2011	13/082,502	2012-0257343			Pending

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2-09-003	US	SEMI-CONDUCTOR CHIP WITH COMPRESSIBLE CONTACT STRUCTURE AND ELECTRONIC PACKAGE UTILIZING SAME	7/15/2010	12/836,612	2012-0038046	6/12/2012	8,198,739	Issued
2-09-005	US	ELECTRONIC PACKAGE INCLUDING HIGH DENSITY INTERPOSER AND CIRCUITIZED SUBSTRATE ASSEMBLY UTILIZING SAME	11/30/2009	12/592,682	2011-0127664	3/26/2013	8,405,229	Issued
2-09-005D	US	ELECTRONIC PACKAGE INCLUDING HIGH DENSITY INTERPOSER AND CIRCUITIZED SUBSTRATE ASSEMBLY UTILIZING SAME	2/26/2013	13/776,777				Pending
2-09-005A	US	METHOD OF MAKING HIGH DENSITY INTERPOSER AND ELECTRONIC PACKAGE UTILIZING SAME	12/1/2009	12/592,734	2011-0126408	8/21/2012	8,245,392	Issued
2-09-008	US	HIGH DENSITY CONNECTOR FOR INTERCONNECTING FINE PITCH CIRCUIT PACKAGING STRUCTURES	5/28/2010	12/789,642	2010-0323558	7/5/2011	7,972,178	Issued
2-09-009	US	ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	10/22/2010	12/910,020	2012-0162928			Pending
2-09-012	US	LIQUID CRYSTAL POLYMER (LCP) SURFACE LAYER ADHESION ENHANCEMENT	8/4/2011	13/197,804	2013-0033671			Pending
2-09-015	US	METHOD OF SMALL CAVITY FORMATION ON BURIED RESISTOR LAYER USING FUSION BONDING	4/8/2011	13/082,444	2012-0256722			Pending
2-10-001	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC INTERPOSER ASSEMBLY AND METHOD	12/20/2010	12/972,700		10/30/2012	8,299,371	Issued
2-10-001D	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC INTERPOSER ASSEMBLY AND METHOD	9/19/2012	13/622,478				Pending
2-10-002	US	ANTI-TAMPER MICROCHIP PACKAGE BASED ON THERMAL NANOFLUIDS OR FLUIDS	9/17/2010	12/884,421	2012-0068326	10/16/2012	8,288,857	Issued
2-10-003	US	LAND GRID ARRAY (LGA) CONTACT CONNECTOR MODIFICATION	10/14/2010	12/904,305	2012-0243147			Pending
2-10-004	US	CIRCUITIZED SUBSTRATE WITH LOW LOSS CAPACITIVE MATERIAL AND METHOD OF MAKING SAME	10/10/2011	13/269,770				Allowed
2-10-005	US	SOLDER AND ELECTRICALLY CONDUCTIVE ADHESIVE BASED INTERCONNECTS FOR CZT CRYSTAL ATTACH	1/26/2012	13/358,716				Pending
2-10-006	US	CIRCUITIZED SUBSTRATE WITH INTERNAL THIN FILM CAPACITOR AND METHOD OF MAKING SAME	3/8/2011	13/042,578	2012-0228014			Pending
2-10-007	US	POLYDIMETHYLSILOXANE (PDMS) RIGID-FLEX SUBSTRATE FOR ELECTRONICS, ELECTRICALLY CONDUCTIVE ADHESIVE (ECA), AND METHOD FOR MAKING SAME	4/17/2012	13/448,505				Pending
2-10-008	US	METAL BUMP CONTACT FOR FLEXIBLE SUBSTRATES, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/19/2011	13/184,882				Pending
2-10-009	US	ELECTRONIC PACKAGE WITH THERMAL INTERPOSER AND METHOD OF MAKING SAME	2/8/2011	13/022,654				Pending
2-10-010	US	ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	4/17/2012	13/448,574				Pending
2-10-011	US	INTEGRATED CIRCUIT DIE COVER PLATE AND THERMAL ADHESIVE FOR ANTI-TAMPERING PACKAGING	5/8/2012	13/466,164				Pending
2-10-012	US	THERMAL SUBSTRATE	7/25/2011	13/189,980				Pending
2-10-013	US	PROCESS TO PURIFY WASTEWATER GENERATED IN THE PROCESS OF HYDRO FRACTURING OF NON-CONVENTIONAL GEOLOGIC FORMATIONS	9/21/2011	13/238,392				Pending
2-10-014	US	MINIATURIZED ELECTRONICS PACKAGE FOR CLANDESTINE USE AND METHOD OF MAKING SAME	1/30/2012	13/360,935				Pending
2-10-015	US	RIGID-FLEX CIRCUIT BOARD	4/16/2012	13/447,701				Pending
2-10-016	US	PROCEDURE TO RUN FOLLOW ON PROCESSES FOR PRODUCT THAT WAS RUN ON THE OPTICAL REGISTRATION SYSTEM AT LAYUP/LAMINATIONS	4/16/2012	13/447,644				Pending
2-10-017	US	METHOD OF MAKING A DIMENSIONALLY STABLE CIRCUITIZED SUBSTRATE	11/21/2012	13/682,805				Pending
2-10-018	US	BUMPED CONNECTION FOR FLEX SUBSTRATES	9/22/2011	13/239,544				Pending
2-10-021	US	CIRCUITIZED SUBSTRATE WITH EMBEDDED CAPACITORS FOR SELF DESTRUCTIVE ANTI-TAMPER PACKAGIN	6/15/2012	13/523,956				Pending

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2-10-022	US	SELF DESTRUCTIVE INTEGRATED CIRCUIT DIE FOR ANTI-TAMPER PACKAGING	5/8/2012	13/466,181				Pending
2-11-006	US	CIRCUITIZED SUBSTRATE INCLUDING RFID TECHNOLOGY AND METHOD OF MAKING SAME	5/30/2012	13/483,600				Pending
2-11-007	US	THIN CORE ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	8/31/2012	13/600,332				Pending
2-11-009	US	METHOD OF VERIFYING PRODUCT AUTHENTICITY	4/17/2012	13/448,778				Pending
2-11-010	US	HIGH PERFORMANCE COMPUTER WITH FIELD PROGRAMMABLE GATE ARRAY ACCELERATION	6/28/2012	13/535,432				Pending